

## CY7C1399BN

#### Features

- Temperature Ranges
  - Industrial: -40°C to 85°C
  - Automotive-A: –40°C to 85°C
- Single 3.3V power supply
- · Ideal for low-voltage cache memory applications
- · High speed: 12 ns
- Low active power
  - 180 mW (max.)
- Low-power alpha immune 6T cell
- Available in Pb-free and non Pb-free Plastic SOJ and TSOP I packages

#### Functional Description<sup>[1]</sup>

The CY7C1399BN is a high-performance 3.3V CMOS Static RAM organized as 32,768 words by 8 bits. Easy memory

#### Logic Block Diagram

# 256K (32K x 8) Static RAM

expansion is provided by an active LOW Chip Enable ( $\overline{CE}$ ) and active LOW Output Enable ( $\overline{OE}$ ) and tristate drivers. The device has an automatic power-down feature, reducing the power consumption by more than 95% when deselected.

An active LOW Write Enable signal ( $\overline{\text{WE}}$ ) controls the writing/reading operation of the memory. When  $\overline{\text{CE}}$  and  $\overline{\text{WE}}$  inputs are both LOW, data on the eight data input/output pins ( $I/O_0$  through  $I/O_7$ ) is written into the memory location addressed by the address present on the address pins ( $A_0$  through  $A_{14}$ ). Reading the device is accomplished by selecting the device and enabling the outputs,  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  active LOW, while  $\overline{\text{WE}}$  remains inactive or HIGH. Under these conditions, the contents of the location addressed by the information on address pins is present on the eight data input/output pins.

The input/output pins remain in a high-impedance state unless the chip is selected, outputs are enabled, and Write Enable (WE) is HIGH. The CY7C1399BN is available in 28-pin standard 300-mil-wide SOJ and TSOP Type I packages.



#### **Pin Configurations**

	SOJ Top Vi	ew	_	
A <sub>5</sub> A <sub>6</sub> A <sub>7</sub> A <sub>8</sub> A <sub>9</sub> A <sub>10</sub> A <sub>11</sub> A <sub>12</sub> A <sub>13</sub> A <sub>14</sub> I/O <sub>1</sub> I/O <sub>1</sub> I/O <sub>2</sub> GND	1 2 3 4 5 6 7 8 9 10 11 12 13 14	28 27 26 25 24 23 22 21 20 19 18 17 16 15		$\begin{array}{c} V_{CC} \\ \hline WE \\ A_4 \\ A_3 \\ A_2 \\ A_1 \\ \hline OE \\ I/O_7 \\ I/O_6 \\ I/O_5 \\ I/O_4 \\ I/O_3 \end{array}$

#### **Selection Guide**

		-12	-15
Maximum Access Time (ns)		12	15
Maximum Operating Current (mA)		55	50
Maximum CMOS Standby Current (µA)	Commercial	500	
	Commercial (L)	50	
	Industrial	500	500
	Automotive-A		500

Note:

1. For guidelines on SRAM system design, please refer to the 'System Design Guidelines' Cypress application note, available on the internet at www.cypress.com.



## **Pin Configuration**

	ISOP op View
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
Ag L 5 A10 L 6 A11 L 7	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$

### **Maximum Ratings**

(Above which the useful life may be impaired. For user guide-lines, not tested.)
Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage on $V_{CC}$ to Relative GND <sup>[2]</sup> –0.5V to +4.6V
DC Voltage Applied to Outputs in High Z State <sup>[2]</sup> 0.5V to $V_{CC}$ + 0.5V DC Input Voltage <sup>[2]</sup> 0.5V to $V_{CC}$ + 0.5V

## Output Current into Outputs (LOW) ...... 20 mA Latch-Up Current ...... >200 mA

## **Operating Range**

Range	Ambient Temperature	v <sub>cc</sub>
Commercial	0°C to +70°C	3.3V ±300 mV
Industrial	–40°C to +85°C	
Automotive-A	–40°C to +85°C	

### Electrical Characteristics Over the Operating Range<sup>[1]</sup>

				-1	2		15	
Parameter	Description	Test Conditions		Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC}$ = Min., $I_{OH}$ = -2.0 mA		2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	$V_{CC}$ = Min., $I_{OL}$ = 4.0 mA			0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage			2.2	V <sub>CC</sub> + 0.3V	2.2	V <sub>CC</sub> + 0.3V	V
V <sub>IL</sub>	Input LOW Voltage <sup>[2]</sup>			-0.3	0.8	-0.3	0.8	V
I <sub>IX</sub>	Input Leakage Current			-1	+1	-1	+1	μA
I <sub>OZ</sub>	Output Leakage Current	$GND \le V_I \le V_{CC},$ Dutput Disabled		-5	+5	-5	+5	μA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	$V_{CC} = Max., I_{OUT} = 0 \text{ mA},$ f = f <sub>MAX</sub> = 1/t <sub>RC</sub>			55		50	mA
I <sub>SB1</sub>	Automatic CE	Max. $V_{CC}, \overline{CE} \ge V_{IH},$	Comm'l		5			mA
	Power-Down Current—	$V_{IN} \ge V_{IH}$ , or $V_{IN} \le V_{IL}$ , f = f <sub>MAX</sub>	Comm'l (L)		4			mA
	TTL Inputs	I – IMAX	Ind'l		5		5	mA
			Auto-A				5	mA
I <sub>SB2</sub>	Automatic CE	Max. $V_{CC}$ , $\overline{CE} \ge V_{CC} - 0.3V$ ,	Comm'l		500			μA
	Power-Down Current— CMOS	$ \begin{array}{l} V_{IN} \geq V_{CC} - 0.3 \text{V, or } V_{IN} \leq 0.3 \text{V,} \\ WE \geq V_{CC} - 0.3 \text{V or } WE \leq 0.3 \text{V,} \\ f = f_{MAX} \end{array} $	Comm'l (L)		50			μA
			Ind'l		500		500	μA
			Auto-A				500	μA

Notes:

Minimum voltage is equal to -2.0V for pulse durations of less than 20 ns.
 Device draws low standby current regardless of switching on the addresses.



### Capacitance<sup>[4]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub> : Addresses	Input Capacitance	$T_{A} = 25^{\circ}C, f = 1 \text{ MHz},$	5	pF
C <sub>IN</sub> : Controls		$V_{CC} = 3.3V$	6	pF
C <sub>OUT</sub>	Output Capacitance		6	pF

#### AC Test Loads and Waveforms<sup>[5]</sup>



### Switching Characteristics Over the Operating Range<sup>[5]</sup>

		-	12	-	15		
Parameter	Description	Min.	Max.	Min.	Max.	Unit	
Read Cycle		ł		•	L		
t <sub>RC</sub>	Read Cycle Time	12		15		ns	
t <sub>AA</sub>	Address to Data Valid		12		15	ns	
t <sub>OHA</sub>	Data Hold from Address Change	3		3		ns	
t <sub>ACE</sub>	CE LOW to Data Valid		12		15	ns	
t <sub>DOE</sub>	OE LOW to Data Valid		5		6	ns	
t <sub>LZOE</sub>	OE LOW to Low Z <sup>[6]</sup>	0		0		ns	
t <sub>HZOE</sub>	OE HIGH to High Z <sup>[6, 7]</sup>		5		6	ns	
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[6]</sup>	3		3		ns	
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[6, 7]</sup>		6		7	ns	
t <sub>PU</sub>	CE LOW to Power-Up	0		0		ns	
t <sub>PD</sub>	CE HIGH to Power-Down		12		15	ns	
Write Cycle <sup>[8,</sup>	9]	•					
t <sub>WC</sub>	Write Cycle Time	12		15		ns	
t <sub>SCE</sub>	CE LOW to Write End	8		10		ns	
t <sub>AW</sub>	Address Set-Up to Write End	8		10		ns	
t <sub>HA</sub>	Address Hold from Write End	0		0		ns	
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		ns	
t <sub>PWE</sub>	WE Pulse Width	8		10		ns	
t <sub>SD</sub>	Data Set-Up to Write End	7		8		ns	
t <sub>HD</sub>	Data Hold from Write End	0		0		ns	
t <sub>HZWE</sub>	WE LOW to High Z <sup>[8]</sup>		7		7	ns	
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[6]</sup>	3		3		ns	

Notes:

Tested initially and after any design or process changes that may affect these parameters.
 Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified

5. Test conditions assume signal transition time of 3 ns or less, timing relefence levels of 1.3v, input puise levels of 0 to 3.vv, and output localing of the specific localing of the



Parameter	Description	Conditions	Min.	Max.	Unit
V <sub>DR</sub>	V <sub>CC</sub> for Data Retention		2.0		V
I <sub>CCDR</sub>	Data Retention Current	$\underline{V_{CC}} = V_{DR} = 2.0V,$	0	20	μΑ
t <sub>CDR</sub>	Chip Deselect to Data Retention Time	$\frac{\overline{CE} \ge V_{CC} - 0.3V}{V_{IN} \ge V_{CC} - 0.3V}$ $\frac{V_{IN} \ge V_{CC} - 0.3V}{V_{IN} \le 0.3V}$	0		ns
t <sub>R</sub>	Operation Recovery Time		t <sub>RC</sub>		ns

#### Data Retention Characteristics (Over the Operating Range - L version only)

### **Data Retention Waveform**



## **Switching Waveforms**





## Read Cycle No. 2<sup>[11, 12]</sup>

#### Notes:

10. Device is continuously selected.  $\overline{OE}$ ,  $\overline{CE} = V_{|L}$ . 11. WE is HIGH for read cycle.

12. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.



## Switching Waveforms (continued)

#### Write Cycle No. 1 (WE Controlled)<sup>[8, 13, 14]</sup>



## Write Cycle No. 2 (CE Controlled)<sup>[8, 13, 14]</sup>



Write Cycle No. 3 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW)<sup>[9, 14]</sup>



#### Notes:

13. Data I/O is high impedance if OE = V<sub>IH</sub>.
 14. If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.

15. During this period, the I/Os are in the output state and input signals should not be applied.



### Truth Table

CE	WE	OE	Input/Output	Mode	Power
Н	Х	Х	High Z	Deselect/Power-Down	Standby (I <sub>SB</sub> )
L	Н	L	Data Out	Read	Active (I <sub>CC</sub> )
L	L	Х	Data In	Write	Active (I <sub>CC</sub> )
L	Н	Н	High Z	Deselect, Output Disabled	Active (I <sub>CC</sub> )

#### **Ordering Information**

Cypress offers other versions of this type of product in many different configurations and features. The following table contains only the list of parts that are currently available.

For a complete listing of all options, visit the Cypress website at www.cypress.com and refer to the product summary page at http://www.cypress.com/products or contact your local sales representative.

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives and distributors. To find the office closest to you, visit us at http://www.cypress.com/go/datasheet/offices.

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
12	CY7C1399BN-12VXC	51-85031	28-Lead Molded SOJ (Pb-free)	Commercial
	CY7C1399BN-12ZXC	51-85071	28-Lead TSOP I (Pb-free)	
	CY7C1399BNL-12ZXC		28-Lead TSOP I (Pb-free)	
	CY7C1399BN-12VXI	51-85031	28-Lead Molded SOJ (Pb-free)	Industrial
15	CY7C1399BN-15ZXI	51-85071	28-Lead TSOP I (Pb-free)	Industrial
	CY7C1399BN-15VXA	51-85031	28-Lead Molded SOJ (Pb-free)	Automotive-A

Please contact local sales representative regarding availability of these parts.

#### **Ordering Code Definitions**





## Package Diagrams

#### NDTE :

#### 28-Lead (300-Mil) Molded SOJ (51-85031)

- 1. JEDEC STD REF MO088
- 2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.006 in (0.152 mm) PER SIDE
- 3. DIMENSIONS IN INCHES MIN.



28-Lead TSOP 1 (8x13.4 mm) (51-85071)



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## **Document History Page**

	Document Title: CY7C1399BN 256K (32K x 8) Static RAM Document Number: 001-06490						
REV.	ECN NO.	ISSUE DATE	ORIG. OF CHANGE	DESCRIPTION OF CHANGE			
**	423877	See ECN	NXR	New Data Sheet			
*A	498575	See ECN	NXR	Added Automotive-A range Removed I <sub>OS</sub> parameter from DC Electrical Characteristics table Updated Ordering Information table.			
*B	2896382	03/19/2010	AJU	Removed obsolete part numbers from Ordering Information table and updated package diagrams.			
*C	3053362	10/08/2010	PRAS	Removed pruned part numbers CY7C1399BNL-15VXC and CY7C1399BNL-15VXCT. Added Ordering Code Definitions.			